

Title (en)
High dielectric constant flexible polyimide film and process of preparation

Title (de)
Flexible Polyimidfolie mit hoher dielektrischer Konstante

Title (fr)
Film de polyimide flexible à constante diélectrique élevée

Publication
EP 0902048 B1 20051123 (EN)

Application
EP 98302799 A 19980409

Priority
US 92798297 A 19970911

Abstract (en)
[origin: US6150456A] A flexible, high dielectric constant polyimide film composed of either a single layer of an adhesive thermoplastic polyimide film or a multilayer polyimide film having adhesive thermoplastic polyimide film layers bonded to one or both sides of the film and having dispersed in at least one of the polyimide layers from 4 to 85 weight % of a ferroelectric ceramic filler, such as barium titanate or polyimide coated barium titanate, and having a dielectric constant of from 4 to 60. The high dielectric constant polyimide film can be used in electronic circuitry and electronic components such as multilayer printed circuits, flexible circuits, semiconductor packaging and buried film capacitors.

IPC 1-7
C08K 3/24; **C08K 3/22**; **B32B 27/30**; **B32B 27/34**; **B32B 15/08**; **H05K 1/16**

IPC 8 full level
C08J 5/18 (2006.01); **B32B 27/18** (2006.01); **B32B 27/34** (2006.01); **C08K 3/22** (2006.01); **C08K 9/00** (2006.01); **C08L 79/08** (2006.01); **H05K 1/03** (2006.01); **H05K 1/16** (2006.01); **H05K 3/38** (2006.01); **H05K 3/46** (2006.01)

CPC (source: EP KR US)
B32B 15/08 (2013.01 - US); **B32B 15/20** (2013.01 - US); **B32B 27/08** (2013.01 - US); **B32B 27/20** (2013.01 - US); **B32B 27/281** (2013.01 - KR US); **B32B 27/34** (2013.01 - EP US); **C08J 5/18** (2013.01 - KR); **C08K 3/24** (2013.01 - EP US); **C08L 79/08** (2013.01 - KR); **H05K 1/0373** (2013.01 - EP US); **H05K 1/162** (2013.01 - EP US); **B32B 2255/20** (2013.01 - US); **B32B 2307/204** (2013.01 - US); **B32B 2379/08** (2013.01 - US); **B32B 2457/08** (2013.01 - US); **B32B 2457/16** (2013.01 - US); **C08J 2300/22** (2013.01 - KR); **C08L 2203/16** (2013.01 - KR); **H05K 1/0346** (2013.01 - EP US); **H05K 3/386** (2013.01 - EP US); **H05K 3/4611** (2013.01 - EP US); **H05K 2201/0154** (2013.01 - EP US); **H05K 2201/0209** (2013.01 - EP US); **H05K 2201/0355** (2013.01 - EP US); **H05K 2201/09309** (2013.01 - EP US); **Y10T 428/252** (2015.01 - EP US); **Y10T 428/2852** (2015.01 - EP US); **Y10T 428/2896** (2015.01 - EP US); **Y10T 428/31721** (2015.04 - EP US)

C-Set (source: EP US)
C08K 3/24 + **C08L 79/08**

Cited by
US8323802B2; EP1650249A1; EP1020487A4; EP2255961A1; US2009263639A1; EP1195882A3; EP1198532A4; EP1422055A4; EP2239305A1; US6577492B2; US7476339B2; WO2013003397A3; US6274224B1; US6638378B2; WO2024064585A1; US7473652B2; US7279777B2; US7098525B2

Designated contracting state (EPC)
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US 6150456 A 20001121; DE 69832444 D1 20051229; DE 69832444 T2 20060803; EP 0902048 A1 19990317; EP 0902048 B1 20051123; JP 3133976 B2 20010213; JP H11106650 A 19990420; KR 100284461 B1 20010302; KR 19990029156 A 19990426; TW 528775 B 20030421; US 6159611 A 20001212

DOCDB simple family (application)
US 31218599 A 19990514; DE 69832444 T 19980409; EP 98302799 A 19980409; JP 9963098 A 19980410; KR 19980012750 A 19980410; TW 87109894 A 19980619; US 22210398 A 19981229